

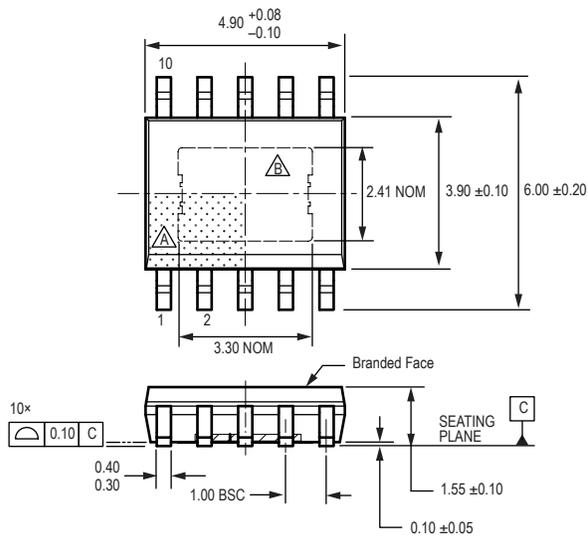
For Reference Only – Not for Tooling Use

(Reference DWG-0000380, Rev. 1)

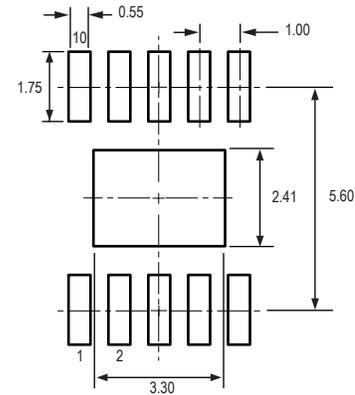
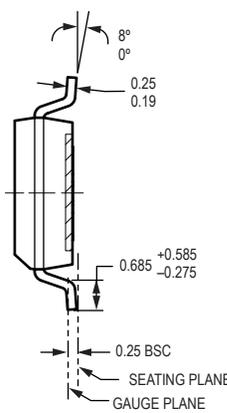
NOT TO SCALE

Dimensions in millimeters

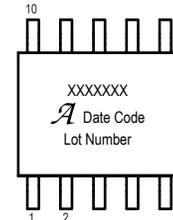
Dimensions exclusive of mold flash, gate burrs, and dambar protrusions
Exact case and lead configuration at supplier discretion within limits shown



-  Terminal #1 mark area
-  Exposed thermal pad (bottom surface)
-  Reference land pattern layout; all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)
-  Branding scale and appearance at supplier discretion



 PCB Layout Reference View



 Standard Branding Reference View

Line 1, 2: Maximum 7 characters per line
Line 3: Maximum 5 characters

Line 1: Part Number
Line 2: Logo A, 4-digit Date Code
Line 3: Characters 5, 6, 7, 8 of Assembly Lot Number

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